



Initial Product/Process Change Notification

Document #: IPCN25630X1

Issue Date: 11 Nov 2025

Title of Change:	Update to IPCN25630X - Cancellation of Carmona Leadframe Consolidation SOIC 14 & 16
Proposed First Ship date:	N/A
Contact Information:	Contact your local onsemi Sales Office
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact
Marking of Parts/ Traceability of Change:	Change in leadframe can be identified by date code.
Change Category:	Assembly Change
Change Sub-Category(s):	Leadframe flag size

Sites Affected:

onsemi Sites	External Foundry/Subcon Sites
onsemi Carmona, Philippines	None

Description and Purpose:

onsemi would like to inform customers of the cancellation of the previously proposed Leadframe Consolidation for SOIC 14 & 16 at the Carmona site.

Qualification Plan:

Not Applicable.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
NLV14076BDR2G	NA
MC14018BDR2G	NA
MC14018BDG	NA
MC14503BDR2G	NA
MC14503BDG	NA



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MC14516BDR2G	NA
MC14516BDG	NA
MC14504BDR2G	NA
MC14504BDG	NA
MC14094BDG	NA
MC14094BDR2G	NA
MC14022BDG	NA
MC14022BDR2G	NA
MC14015BDG	NA
MC10EL57DR2G	NA
MC100EL15DR2G	NA
MC10EL15DR2G	NA
LM2901EDR2G	NA
MC14541BDR2G	NA
MC14066BDR2G	NA
LM324ADR2G	NA
MC14066BDG	NA
MC3303DR2G	NA
MC14013BDR2G	NA
MC14013BDG	NA
MC14541BDG	NA
MC33079DR2G	NA
MC33179DR2G	NA
MC3403DR2G	NA
MC14106BDR2G	NA
MC14106BDG	NA
SC2902DR2G	NA
MC33274ADR2G	NA
LMV824DR2G	NA
MC33074DR2G	NA
MC33074ADR2G	NA
MC33174DR2G	NA
MC33174VDR2G	NA
MC33204DR2G	NA



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MC34074VDR2G	NA
MC34074ADR2G	NA
MC34074DR2G	NA
CS3351YDR14G	NA
LM339DR2G	NA
LM2901DR2G	NA
LM2901VDR2G	NA
LM2902VDR2G	NA
MC3302DR2G	NA
LM239DR2G	NA
LM224DR2G	NA
MC14082BDR2G	NA
TLV274DR2G	NA
NCS20074DR2G	NA
NCS20034DR2G	NA
LM324EDR2G	NA
LM2902EDR2G	NA
LM339EDR2G	NA
MC100LVEL34DR2G	NA
NB4N507ADR2G	NA
NCP1034DR2G	NA
MC100LVEP34DG	NA
NCP1562ADR2G	NA
NCP1562BDR2G	NA
MC100EL15DG	NA
MC100EL57DG	NA
MC10EL34DG	NA
MC1413DR2G	NA
ULN2003ADR2G	NA
ULQ2003ADR2G	NA
MC1413BDR2G	NA
NCP1631DR2G	NA
TL494BDR2G	NA
TL594CDR2G	NA



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TL494CDR2G	NA
MC14052BDR2G	NA
MC14551BDR2G	NA
MC14051BDR2G	NA
MC14052BDG	NA
MC14551BDG	NA
MC14051BDG	NA
MC14538BDR2G	NA
MC14538BDG	NA
MC14528BDR2G	NA
MC14528BDG	NA
MC14053BDR2G	NA
MC14053BDG	NA
MC14017BDG	NA
MC14017BDR2G	NA
NCL30001DR2G	NA
MC14521BDR2G	NA
MC14521BDG	NA
MC14040BDR2G	NA
MC14040BDG	NA
MC14076BDR2G	NA
MC14543BDG	NA
MC14543BDR2G	NA
MC14585BDR2G	NA
MC14008BDR2G	NA
MC14532BDR2G	NA
MC14532BDG	NA
MC14028BDR2G	NA
MC14512BDR2G	NA
MC14014BDR2G	NA
MC14014BDG	NA
MC14021BDR2G	NA
MC14021BDG	NA
MC14043BDG	NA



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MC14044BDG	NA
MC14043BDR2G	NA
MC14044BDR2G	NA
NE5517DR2G	NA
MC14015BDR2G	NA
MC14060BDG	NA
MC14060BDR2G	NA
MC14511BDR2G	NA
MC14511BDG	NA
MC14029BDR2G	NA
MC14020BDR2G	NA



Initial Product/Process Change Notification

Document #: IPCN25630X

Issue Date: 19 Sep 2023

Title of Change:	Carmona Leadframe Consolidation SOIC 14 & 16
Proposed First Ship date:	08 Nov 2024 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office or
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact
Marking of Parts/ Traceability of Change:	Change in leadframe can be identified by date code.
Change Category:	Assembly Change
Change Sub-Category(s):	Leadframe flag size

Sites Affected:

onsemi Sites	External Foundry/Subcon Sites
onsemi Carmona, Philippines	None

Description and Purpose:

Leadframe consolidation resulting in change to flag size dimension.

	From	To
Leadframe	SOIC 14L Set A Flag Size (mils) 100x160, 100x150, 90x130, 90x90, 90x130	Flag Size 100x160mils
	SOIC 14 Set B Flag Size (mils) 70x70, 55x63, 37x37, 55x63	Flag Size 70x70mils
	SOIC 16 Flag size (mils) 70x70, 90x90, 90x130, 94x100, 100x150	Flag size 100x150mils

There are no product material changes as a result of this change.

There is no product marking change as a result of this change. Change in leadframe flag size is identifiable by date code.



Initial Product/Process Change Notification

Document #: IPCN25630X

Issue Date: 19 Sep 2023

Qualification Plan:

QV DEVICE NAME: LM339DR2G

RMS:

PACKAGE: SOIC 14

Test	Specification	Condition	Interval
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Preconditioning	J-STD-020, JESD-A113	MSL 1 @ 260°C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
Solderability	JSTD002	Ta = 245°C, 5 sec	
Physical Dimensions	JESD22-B100 and B108		

QV DEVICE NAME: NLV14014BDR2G_NLV14094BDR2G

RMS: TBD

PACKAGE: SOIC 16

Test	Specification	Condition	Interval
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
Solderability	JSTD002	Ta = 245°C, 5 sec	
Physical Dimensions	JESD22-B100 & B108		

QV DEVICE NAME: NLV14572UBDR2G_NCV1413BDR2G

RMS: TBD

PACKAGE: SOIC 16

Test	Specification	Condition	Interval
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
Solderability	JSTD002	Ta = 245°C, 5 sec	
Physical Dimensions	JESD22-B100 & B108		



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Document #: IPCN25630X

Issue Date: 19 Sep 2023

QV DEVICE NAME: MC100LVEL34DR2G_ NCV1034DR2G

RMS: TBD

PACKAGE: SOIC 16

Test	Specification	Condition	Interval
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
Solderability	JSTD002	Ta = 245°C, 5 sec	
Physical Dimensions	JESD22-B100 & B108		

QV DEVICE NAME: NCV20034DR2G

NCV20074DR2G - HAST

RMS:

PACKAGE: SOIC 14

Test	Specification	Condition	Interval
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Preconditioning	J-STD-020, JESD-A113	MSL 1 @ 260°C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
Solderability	JSTD002	Ta = 245°C, 5 sec	
Physical Dimensions	JESD22-B100 and B108		

QV DEVICE NAME: NLV14012BDR2G

RMS:

PACKAGE: SOIC 14

Test	Specification	Condition	Interval
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Preconditioning	J-STD-020, JESD-A113	MSL 1 @ 260°C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
Solderability	JSTD002	Ta = 245°C, 5 sec	
Physical Dimensions	JESD22-B100 and B108		



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Issue Date: 19 Sep 2023

QV DEVICE NAME: SCV209D2R2G / LMV824DR2G

RMS: TBD

PACKAGE: SOIC 14

Test	Specification	Condition	Interval
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Preconditioning	J-STD-020, JESD-A113	MSL 3 @ 260°C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
Solderability	JSTD002	Ta = 245°C, 5 sec	
Physical Dimensions	JESD22-B100 and B108		

QV DEVICE NAME: NCV2902DR2G

RMS: TBD

PACKAGE: SOIC 14

Test	Specification	Condition	Interval
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Preconditioning	J-STD-020, JESD-A113	MSL 1 @ 260°C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
Solderability	JSTD002	Ta = 245°C, 5 sec	
Physical Dimensions	JESD22-B100 and B108		

QV DEVICE NAME: NLV14013BDR2G

RMS: TBD

PACKAGE: SOIC 14

Test	Specification	Condition	Interval
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Preconditioning	J-STD-020, JESD-A113	MSL 1 @ 260°C	
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
Solderability	JSTD002	Ta = 245°C, 5 sec	
Physical Dimensions	JESD22-B100 and B108		

Estimated date for qualification completion: 29 March 2024



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List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
MC14541BDR2G	NLV14013BDR2G
MC14066BDR2G	NLV14013BDR2G
LM324ADR2G	NLV14013BDR2G
MC14066BDG	NLV14013BDR2G
MC3303DR2G	NLV14013BDR2G
MC14013BDR2G	NLV14013BDR2G
MC14013BDG	NLV14013BDR2G
MC14541BDG	NLV14013BDR2G
MC33079DR2G	NLV14013BDR2G
MC33179DR2G	NLV14013BDR2G
MC3403DR2G	NLV14013BDR2G
MC14106BDR2G	NLV14013BDR2G
MC14106BDG	NLV14013BDR2G
SC2902DR2G	NCV2902DR2G
MC33274ADR2G	NLV14013BDR2G
LMV824DR2G	SCV209D2R2G_LMV824DR2G
MC33074DR2G	NLV14013BDR2G
MC33074ADR2G	NLV14013BDR2G
MC33174DR2G	NLV14013BDR2G
MC33174VDR2G	NLV14013BDR2G
MC33204DR2G	NLV14013BDR2G
MC34074VDR2G	NLV14013BDR2G
MC34074ADR2G	NLV14013BDR2G
MC34074DR2G	NLV14013BDR2G
CS3351YDR14G	SCV209D2R2G_LMV824DR2G
LM339DR2G	LM339DR2G
LM2901DR2G	LM339DR2G
LM2901VDR2G	LM339DR2G
LM2902VDR2G	LM339DR2G



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MC3302DR2G	LM339DR2G
LM239DR2G	LM339DR2G
LM224DR2G	LM339DR2G
MC14082BDR2G	NLV14012BDR2G
TLV274DR2G	NCV20034DR2G_NCV20074DR2G
NCS20074DR2G	NCV20034DR2G_NCV20074DR2G
NCS20034DR2G	NCV20034DR2G_NCV20074DR2G
LM324EDR2G	LM339DR2G
LM2902EDR2G	LM339DR2G
LM339EDR2G	LM339DR2G
LM2901EDR2G	LM339DR2G
MC100LVEL34DR2G	MC100LVEL34DR2G
NB4N507ADR2G	MC100LVEL34DR2G_NCV1034DR2G
NCP1034DR2G	MC100LVEL34DR2G_NCV1034DR2G
MC10EL15DR2G	MC100LVEL34DR2G_NCV1034DR2G
MC100LVEP34DG	MC100LVEL34DR2G_NCV1034DR2G
NCP1562ADR2G	MC100LVEL34DR2G_NCV1034DR2G
NCP1562BDR2G	MC100LVEL34DR2G_NCV1034DR2G
MC100EL15DG	MC100LVEL34DR2G_NCV1034DR2G
MC100EL15DR2G	MC100LVEL34DR2G_NCV1034DR2G
MC100EL57DG	MC100LVEL34DR2G_NCV1034DR2G
MC10EL34DG	MC100LVEL34DR2G_NCV1034DR2G
MC10EL57DR2G	MC100LVEL34DR2G_NCV1034DR2G
MC1413DR2G	NLV14572UBDR2G_NCV1413BDR2G
ULN2003ADR2G	NLV14572UBDR2G_NCV1413BDR2G
ULQ2003ADR2G	NLV14572UBDR2G_NCV1413BDR2G
MC1413BDR2G	NLV14572UBDR2G_NCV1413BDR2G
NCP1631DR2G	NLV14014BDR2G_NLV14094BDR2G
TL494BDR2G	NLV14014BDR2G_NLV14094BDR2G
TL594CDR2G	NLV14014BDR2G_NLV14094BDR2G
TL494CDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14052BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14551BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14051BDR2G	NLV14014BDR2G_NLV14094BDR2G



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MC14052BDG	NLV14014BDR2G_NLV14094BDR2G
MC14551BDG	NLV14014BDR2G_NLV14094BDR2G
MC14051BDG	NLV14014BDR2G_NLV14094BDR2G
MC14538BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14538BDG	NLV14014BDR2G_NLV14094BDR2G
MC14528BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14528BDG	NLV14014BDR2G_NLV14094BDR2G
MC14053BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14053BDG	NLV14014BDR2G_NLV14094BDR2G
MC14017BDG	NLV14014BDR2G_NLV14094BDR2G
MC14017BDR2G	NLV14014BDR2G_NLV14094BDR2G
NCL30001DR2G	NLV14014BDR2G_NLV14094BDR2G
MC14521BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14521BDG	NLV14014BDR2G_NLV14094BDR2G
MC14040BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14040BDG	NLV14014BDR2G_NLV14094BDR2G
MC14020BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14029BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14511BDG	NLV14014BDR2G_NLV14094BDR2G
MC14511BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14060BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14060BDG	NLV14014BDR2G_NLV14094BDR2G
MC14018BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14018BDG	NLV14014BDR2G_NLV14094BDR2G
MC14503BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14503BDG	NLV14014BDR2G_NLV14094BDR2G
MC14516BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14516BDG	NLV14014BDR2G_NLV14094BDR2G
MC14504BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14504BDG	NLV14014BDR2G_NLV14094BDR2G
MC14094BDG	NLV14014BDR2G_NLV14094BDR2G
MC14094BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14022BDG	NLV14014BDR2G_NLV14094BDR2G
MC14022BDR2G	NLV14014BDR2G_NLV14094BDR2G



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MC14015BDG	NLV14014BDR2G_NLV14094BDR2G
MC14015BDR2G	NLV14014BDR2G_NLV14094BDR2G
NE5517DR2G	NLV14014BDR2G_NLV14094BDR2G
MC14044BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14043BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14044BDG	NLV14014BDR2G_NLV14094BDR2G
MC14043BDG	NLV14014BDR2G_NLV14094BDR2G
MC14021BDG	NLV14014BDR2G_NLV14094BDR2G
MC14021BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14014BDG	NLV14014BDR2G_NLV14094BDR2G
MC14014BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14512BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14028BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14532BDG	NLV14014BDR2G_NLV14094BDR2G
MC14532BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14008BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14585BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14543BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14543BDG	NLV14014BDR2G_NLV14094BDR2G
NLV14076BDR2G	NLV14014BDR2G_NLV14094BDR2G
MC14076BDR2G	NLV14014BDR2G_NLV14094BDR2G
LM339DR2GH	LM339DR2G